100% Material Declaration Data Sheet CSG144

Average Weight: 0.3 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.01818**	**6.06%**
	Silicon	7440-21-3	100.00		0.01818	
Die Attach Material					**0.00099**	**0.33%**
	Silver	7440-22-4	52.00		0.0005148	
	Resin (EP)	Trade Secret	48.00		0.0004752	
Encapsulant					**0.15591**	**51.97%**
	Epoxy Resins	Trade Secret	6.00		0.0093546	
	Phenolic Resins	Trade Secret	6.00		0.0093546	
	Carbon Black	1333-86-4	0.50		0.00077955	
	Silica	60676-86-0	84.00		0.1309644	
	Bismuth	7440-69-9	Max 1.00		0.0015591	
	Metal Hydroxide	Trade Secret	2.50		0.00389775	
Tape					**0.01794**	**5.98%**
	Polymide	Trade Secret	41.51		0.007446894	
	Adhesive	Trade Secret	58.49		0.010493106	
Metal Layers					**0.03285**	**10.95%**
	Copper	7440-50-8	88.32		0.02901312	
	Nickel	7440-02-0	7.90		0.00259515	
	Gold	7440-57-5	3.78		0.00124173	
Bond Wire					**0.00261**	**0.87%**
	Gold	7440-57-5	100.00		0.00261	
Solder Balls					**0.07152**	**23.84%**
	Tin	7440-31-5	95.50		0.0683016	
	Silver	7440-22-4	4.00		0.0028608	
	Copper	7440-50-8	0.50		0.0003576	

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Xilinx believes this environmental information to be correct, but cannot guarantee its completeness or accuracy as it is based on data received from sources outside our company.

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/20/06	1.0	Initial release.
6/29/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.